

**LINEAR TECHNOLOGY MATERIALS DECLARATION**

1t3032ide-15#trpbf

(Engineering Calculation)

DFN 4mm X 3mm Exp. Pad

(printed on: 2020-07-11 20:25:23)

**TOTAL MASS (g) : 0.030154**

COMPONENT MATERIAL	VENDOR/ INDUSTRY NAMES	CONSTITUENT NAME	CAS NUMBER	CONSTITUENT MASS (g)	CONSTITUENT (PPM) OF MATERIAL	CONSTITUENT (PPM) OF TOTAL PKG.		
Active Device	Linear Technology	Silicon (Si)	7440-21-3	0.000673	1000000	22318.9355469		
Die Coat	Dow Corning	Silicone	69430-27-9	0.000000	0	0		
Lead Frame	Cu	Copper (Cu)	7440-50-8	0.013131	974800.0625	435467.96875		
		Iron (Fe)	7439-89-6	0.000317	23500	10512.7822266		
		Phosphorus (P)	7723-14-0	0.000011	850	364.796875		
		Zinc (Zn)	7440-66-6	0.000011	850	364.796875		
		Nickel (Ni)	7440-02-0	0.000000	0	0		
		Silicon (Si)	7440-21-3	0.000000	0	0		
		Magnesium (Mg)	7439-95-4	0.000000	0	0		
		Tin (Sn)	7440-31-5	0.000000	0	0		
<b>Lead Frame Total:</b>				<b>0.013470</b>	<b>1000000</b>	<b>446710.3125</b>		
Plating	PMI	Exter. Plating Pb	7439-92-1	0.000000	0	0		
		Exter. Plating Sn	7440-31-5	0.000626	1000000	20752.5878906		
		<b>External Plating Total:</b>				<b>0.000626</b>	<b>1000000</b>	<b>20752.5878906</b>
		Inter. Plating Ni	7440-02-0	0.000000	0	0		
		Inter. Plating Ag	7440-22-4	0.000302	1000000	10015.3320312		
<b>Internal Plating Total:</b>				<b>0.000302</b>	<b>1000000</b>	<b>10015.3320312</b>		
Die Attach	ELECTRICALLY CONDUCTIVE ADHESIVE	Silver (Ag)	7440-22-4	0.000448	750000	14857.1816406		
		Tin (Sn)	7440-31-5	0.000000	0	0		
		Lead (Pb)	7439-92-1	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.000000	0	0		
		Indium (In)	7440-74-6	0.000000	0	0		
		Metal Oxide		0.000000	0	0		
		Antimony (Sb)	7440-36-0	0.000000	0	0		
		Resin (EP)		0.000149	250000	4941.33935547		
<b>Die Attach Total:</b>				<b>0.000597</b>	<b>1000000</b>	<b>19798.5214844</b>		
Encapsulation	MULTI-AROMATIC RESIN Br/Sb FREE	Resin (EP)		0.001876	130000	62214.4453125		
		Bromine (Br)	40039-93-8	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.012410	860000	411557.1875		
		Antimony Trioxide (Sb2O3)	1309-64-4	0.000000	0	0		
		Metal Hydroxide		0.000000	0	0		
		Carbon Black (C)	1333-86-4	0.000144	10000	4775.52294922		
		<b>Encapsulation Total:</b>				<b>0.014430</b>	<b>1000000</b>	<b>478547.1875</b>
Bond Wire Estimated	AFW/TANAKA/ Kn	Gold (Au)	7440-57-5	0.000056	1000000	1857.14770508		
					<b>TOTAL MASS (g) :</b>	<b>0.030154</b>		